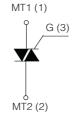
RoHS



LOGIC LEVEL TRIAC

TO-263AB / D2PAK





On-State Current

8 Amp

Gate Trigger Current

≤ 10 mA (09) ≤ 7 mA (07) ≤ 5 mA (04)

Off-State Voltage

200 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Ideal for automated placement
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-263AB / D2PAK. Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

Logic level versions are designed to interface directly with low power drivers such as microcontrollers.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c =95 °C	8	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	88	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	80	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	32	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
$P_{G(AV)}$	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL PARAMETER	PARAMETER	VOLTAGE					Unit
OTNIBOL	17404012121	В	D	М	S	N	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	200	400	600	700	800	V

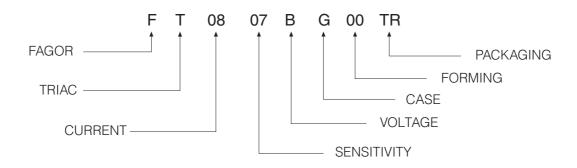


Electrical Characteristics at Tamb = 25 °C

SYMBOL	PARAMETER	CONDITIONS	Quadrant	Quadrant		ENSITIVITY		1.1
STIVIBOL	FANAIVILTEN	CONDITIONS	Quaurant		04 *	07	09	Unit
I _{GT} (1)	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25$	5°C Q1÷Q3	MAX	5	5	10	mA
			Q4	MAX	-	7	10	mA
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25$	5°C Q1÷Q3	MAX		1.3		V
			Q1÷Q4	MAX		1.3		V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ K}\Omega, T_j = 125$	s°C Q1÷Q3	MIN		0.2		V
			Q1÷Q4	MIN		0.2	l	V
I _H ⁽²⁾	Holding Current	$I_T = 100 \text{ mA}$, Gate open, $T_j = 25$	5°C	MAX	15	15	20	mA
IL	Latching Current	$I_{G} = 1.2 I_{GT}, T_{j} = 25 ^{\circ}\text{C}$	Q1,Q3 Q1, Q3, Q4	MAX	25 -	- 20	- 20	mA mA
			Q1, Q3, Q4 Q2	MAX	30	30	25	mA
dV/dt (2)	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Gate open		MIN	40	20	40	V/µs
		T _j = 125 °C						
(dl/dt)c (2)	Critical Rate of Current Rise	, , ,	1	MIN	5.4	1.8	2.5	A/ms
		$(dv/dt)c = 10 V/\mu s$ $T_j = 125$		MIN	2.8	0.9	1.5	A/ms
V _{TM} ⁽²⁾	On state Valta are	without snubber $T_j = 125$		MIN	-	- 10	-	\ \ \
V _{t (o)} (2)	On-state Voltage	$I_T = 11 \text{ Amp, tp} = 380 \text{ µs, } T_j = 25$		MAX		1.6		V
$r_d^{(2)}$	Threshold Voltage Dynamic resistance	$T_j = 125 ^{\circ}\text{C}$ $T_i = 125 ^{\circ}\text{C}$		MAX		0.85		$m\Omega$
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}, T_i = 125$. °C	MAX		1		mA
I IDRM/IRRM	OII-State Leakage Guilett	$V_R = V_{RRM}$, $T_j = 125$		MAX		5		μΑ
R _{th(j-c)}	Thermal Resistance	for AC 360° conduction angle	, 5	INICAN		1.6		°C/W
· 'tm(j-c)	Junction-Case	101710 300 Conduction angle				1.0		0, ••
R _{th(j-a)}	Thermal Resistance							
r un(j-a)	Junction-Ambient	$S = 1 \text{ cm}^2$				45		°C/W

⁽¹⁾ Minimum I_{GT} is guaranted at 5% of I_{GT} max.

Part Number Information



⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.

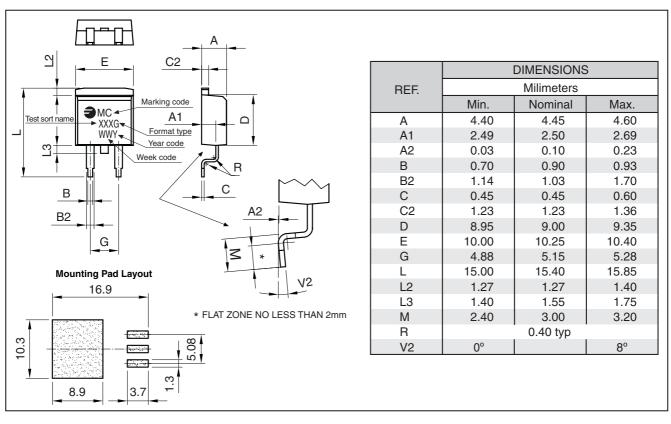
^{*} Sensitivity group 04 maximum Vdrm: 600V.



Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	UNIT WEIGHT (g)	
FT0809MG 00TR	TR	13" diameter tape and reel	800	1.50

Package Outline Dimensions: (mm) TO-263AB / D2PAK





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state curren (full cycle).

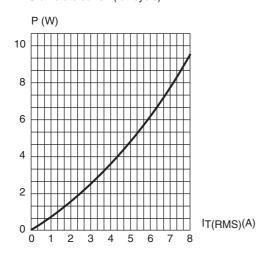


Fig. 3: Relative variation of thermal impedance versus pulse duration.

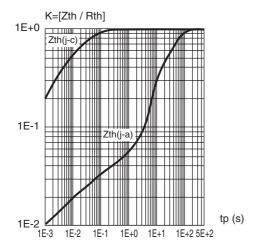


Fig. 5: Surge peak on-state current versus number of cycles

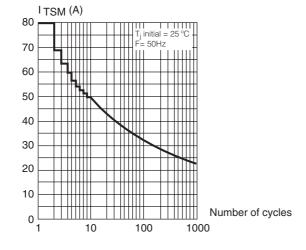


Fig. 2: RMS on-state current versus case temperature (full cycle).

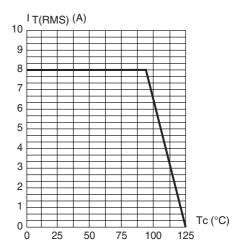


Fig. 4: On-state characteristics (maximum values)

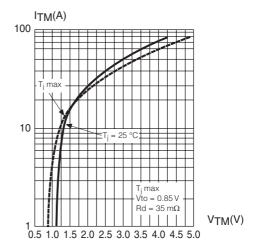
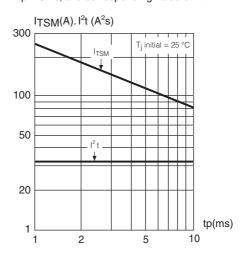


Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponding value of I²t.





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

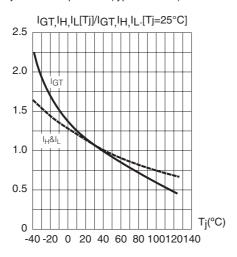


Fig. 9: Relative variation of critical rate of decrease of main current versus

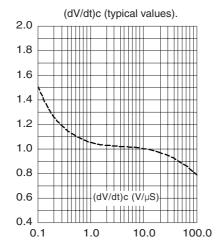
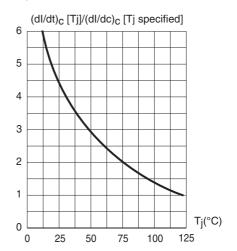


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature





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